

SOT916-1

plastic thermal enhanced thin quad flat package; no leads; 56 terminals; body 9 x 9 x 1.1 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HTQFN56R
Package type industry code	HTQFN56R
Package style descriptive code	HTQFN (thermal enhanced thin quad flatpack; no leads)
Package style suffix code	R (resin based)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-11-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	8.9	-	9	9.1	mm
E	package width	8.9	-	9	9.1	mm
A	seated height	[tbd]	-	1.1	1.2	mm
A ₂	package height	[tbd]	-	1.1	1.2	mm
n ₂	actual quantity of termination	-	-	56	-	

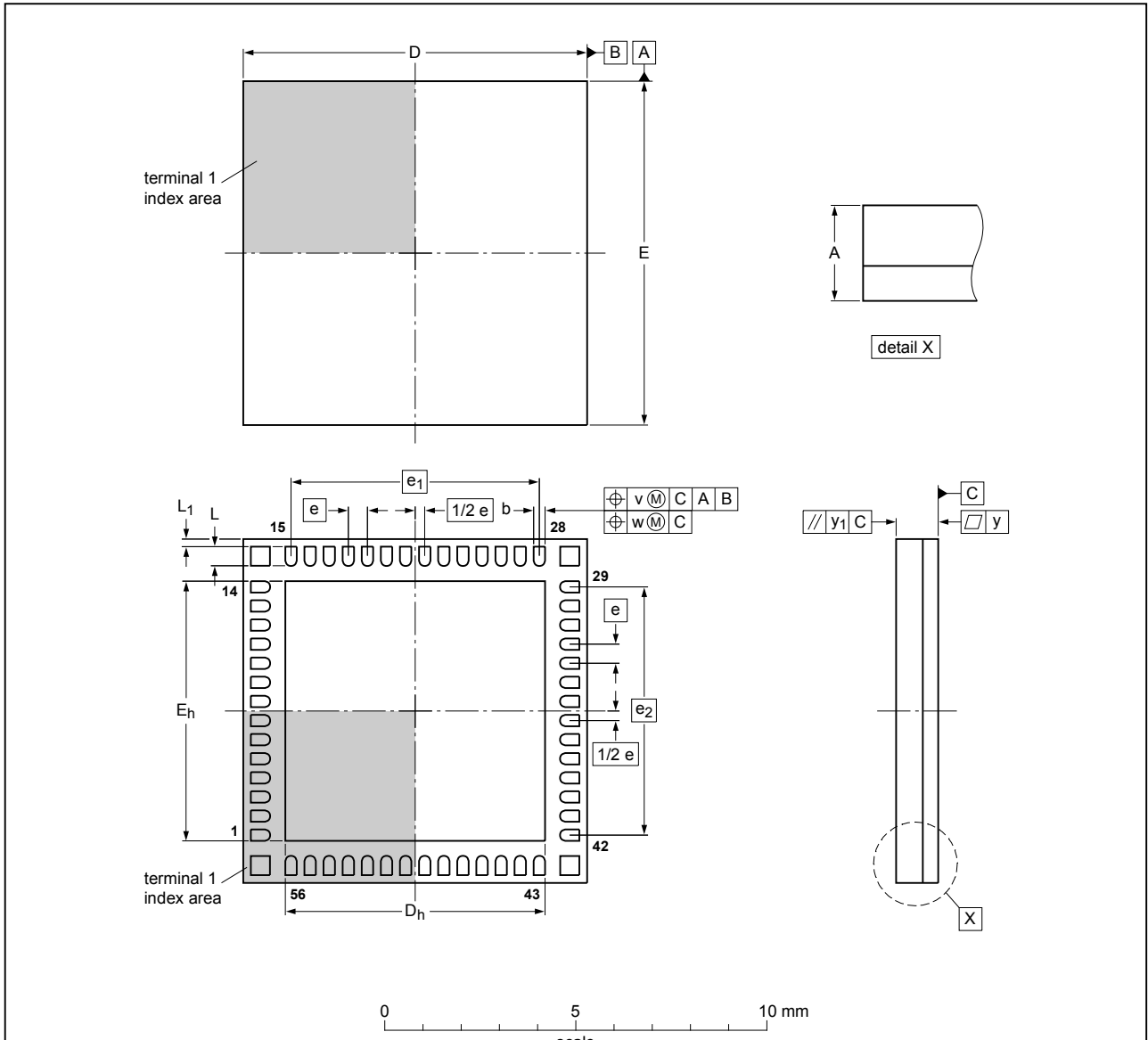


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2. Package outline

HTQFN56R: plastic thermal enhanced thin quad flat package; no leads;
56 terminals; resin based; body 9 x 9 x 1.1 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	b	D	D _h	E	E _h	e	e ₁	e ₂	L	L ₁	v	w	y	y ₁
mm	1.2	0.32 0.28	9.1 8.9	6.95 6.65	9.1 8.9	6.95 6.65	0.5	6.5	6.5	0.6 0.4	0.26 0.10	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT916-1	---	---	---			05-11-14 07-11-14

Fig. 1. Package outline HTQFN56R (SOT916-1)

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3. Legal information

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